

ABSTRACT OF THE DISCLOSURE

The chip package and the process thereof are disclosed. In the chip package, a rigid cover is disposed on the active surface of the chip to protect the active surface of the chip and enhance the structural strength of the chip package. Further, if the material of the rigid cover is a thermal conductive material such as Cu or Al alloy, the heat-spread ability of the chip package can be enhanced. If the rigid cover is made of an electrical conductive material and electrically connected to the ground, the electromagnetic interference (EMI) to the chip package can be reduced. It should be noted that the chip packaging process can form a plurality of the terminal pads on the backside of the chip so that the chip package can be connected to the PCB or substrate via these terminal pads.